

We use cookies to personalize and enhance your experience on our site. Visit our [Privacy Policy](#) to learn more or manage your personal preferences in our [Cookie Consent Tool](#). By using our site, you agree to our use of cookies.

Accept


Home > Products > DRAM > MT53B256M32D1NP 053 WT

ADD EMAIL    

MT53B256M32D1NP-053 WT

DATA SHEETS (1) | SPECS | SIM MODELS & SOFTWARE | ROHS CERTIFICATES | DOCUMENTATION & SUPPORT | PARTS WITH THE SAME DATA SHEET (5) | WHERE TO BUY | DATA SHEETS (1) | SPECS | SIM MODELS & SOFTWARE

Data Sheets (1)

Data Sheet 

Production Data Sheet: 200-Ball Z01M Embedded LPDDR4 SDRAM

MT53B256M32D1, MT53B512M32D2, MT53B1024M32D4

File Type: PDF Updated: 07/2018

DRAM Embedded Mobile LPDDR4

DOWNLOAD

Specs

Orderable Parts for: MT53B256M32D1NP-053 WT

[SEE ALL 8GB LPDRAM PARTS](#)

	Status	Media	FBGA Code	SPD Data	Chipset Validation	PLP	Start Date	Alternative Part
MT53B256M32D1NP-053 WT:C	Production	N/A	D9VTH	N/A	N/A	No		N/A

Detailed Specifications

Technology	LPDDR4	Density	8Gb	Part Status	Production	RoHS	Yes
Depth	256Mb	Width	x32	Voltage	1.1V	Package	WFBGA
Pin Count	200-ball	Clock Rate	1866 MHz	Data Rate	DDR4-3733	Cycle Time	
Op. Temp.	-30C to +85C	Brand	Micron				

Sim Models & Software

Sim Models

IBIS



Z01M IBIS (ZIP)

DRAM
Mobile LPDDR4

Z01M Mobile LPDDR4 SDRAM, Die Rev. C, SDP, DDP, QDP, 200b, 272b, 366b, 432b

File Type: ZIP

Updated: 07/05/2018

DOWNLOAD

HSpice



Z01M HSPICE (ZIP)

DRAM
Mobile LPDDR4

Z01M Mobile LPDDR4 SDRAM, Die Rev. C

File Type: ZIP

Updated: 03/15/2017

DOWNLOAD

RoHS Certificates

RoHS Certificates

RoHS Certificate of Compliance (PDF)

Part-specific certification of how this product meets the requirements of the current DIRECTIVE 2002/95/EC, a.k.a. Restriction of Hazardous Substances (RoHS) Directive.

File Type: (PDF)

Updated: 07/2018

DOWNLOAD

RoHS Certificates

China RoHS Certificate (PDF)

Part-specific certification as required by China's Management Methods for Controlling Pollution by Electronic Information Products.

File Type: (PDF)

Updated: 07/2018

DOWNLOAD

Documentation & Support

[See All LPDRAM Documentation](#)

Technical Notes

Technical Notes

Technical Note: Low-Power Function of Mobile RAM - Deep Power Down (DPD) (PDF)DRAM
LPDRAM

(E0598E21) This technical note describes Deep Power Down (DPD), one of the low-power functions that have been adapted to Mobile DRAM.

File Type: PDF

Updated: 02/26/2014

[DOWNLOAD](#)

Technical Notes

Technical Note: Low-Power Function of Mobile RAM - Partial Array Self Refresh (PASR) (PDF)DRAM
LPDRAM

(E0597E10) This technical note describes Partial Array Self Refresh (PASR), one of the low-power functions that have been adapted to Mobile DRAM.

File Type: PDF

Updated: 02/26/2014

[DOWNLOAD](#)

Customer Service Notes

[SEE ALL CUSTOMER SERVICE NOTES](#)

Customer Service Note

Product Marks, Product Labels, and Packaging Labels (PDF)3D XPoint
Client
Cloud
Cloud
[See More Tags](#)

(CSN-11) The first section of this customer service note describes the product marks and labels we place on our devices. The second section describes the labels used on and in our packaging.

File Type: PDF

Updated: 03/08/2018

[DOWNLOAD](#)

Customer Service Note

Micron BGA Manufacturer's User Guide (PDF)DDR2 SDRAM
DDR4 SDRAM
Embedded USB
eMMC
[See More Tags](#)

(CSN-33) Provides information to enable customers to easily integrate both leading-edge and legacy Micron's ball grid array (BGA) packages into their manufacturing processes. It is intended as a set of high-level guidelines and a reference manual describing typical package-related and...

File Type: PDF

Updated: 12/10/2014

[DOWNLOAD](#)

Parts with the same Data Sheet (5)


MT53B256M32D1NP-053 WT (Current)		MT53B256M32D1NP-062 WT	MT53B256M32D1DS-062 XT	MT53B512M32D2NP-062 WT
Part Status	Production	Production	Sampling	Production
Technology	LPDDR4	LPDDR4	LPDDR4	LPDDR4
Density	8Gb	8Gb	8Gb	16Gb
RoHS	Yes	Yes	Yes	Yes
Depth	256Mb	256Mb	256Mb	512Mb
Width	x32	x32	x32	x32
Voltage	1.1V	1.1V	1.1V	1.1V
Package	WFBGA	WFBGA	WFBGA	WFBGA
Pin Count	200-ball	200-ball	200-ball	200-ball
Clock Rate	1866 MHz	1600 MHz	1600 MHz	1600 MHz
Data Rate	DDR4-3733	DDR4-3200	DDR4-3200	DDR4-3200
Cycle Time				
Op. Temp.	-30C to +85C	-30C to +85C	-30C to +105C	-30C to +85C
Brand	Micron	Micron	Micron	Micron


MT53B256M32D1NP-053 WT (Current)	
Part Status	Production
Technology	LPDDR4
Density	8Gb
RoHS	Yes
Depth	256Mb
Width	x32
Voltage	1.1V
Package	WFBGA
Pin Count	200-ball

Where to Buy

- OR - Check with Distributors

Your Region:

 [VIEW](#)

 [VIEW](#)

[See All Distributors](#)

Clock Rate	1866 MHz
Data Rate	DDR4-3733
Cycle Time	
Op. Temp.	-30C to +85C
Brand	Micron

[Multichip Packages](#)
[Memory Cards](#)
[Solid State Drives](#)

[Industrial Memory Solutions](#)
[Mobile Memory Solutions](#)
[Networking Innovations](#)

[ns](#)
[stry](#)
[ive Memory Solutions](#)
[er](#)
[ed Memory Solutions](#)
[olutions](#)
[Services](#)

By Application

[Client](#)
[Cloud](#)
[Data Center](#)
[Storage Data Security](#)
[Enterprise SSD Storage](#)
[Supercomputing Memory](#)

Support

[Contact Us](#)
[Support Documentation and Downloads](#)
[Sales Support](#)
[Sales Network](#)
[Authorized Sales](#)
[Authorized Distributors](#)
[Legal](#)
[Site Map](#)
[Surplus Equipment](#)

About

[Our Company](#)
[News and Events](#)
[Micron Blogs](#)
[Jobs](#)
[Micron Foundation](#)
[History of Innovation](#)
[Locations](#)
[Our Commitment](#)
[Investor Relations](#)
[Suppliers](#)



©2018 Micron Technology, Inc. All rights reserved. Information, products, and/or specifications are subject to change without notice. All information is provided on an "AS IS" basis without warranties of any kind. Drawings may not be to scale. Micron, the Micron logo, and all other Micron trademarks are the property of Micron Technology, Inc. All other trademarks are the property of their respective owners.